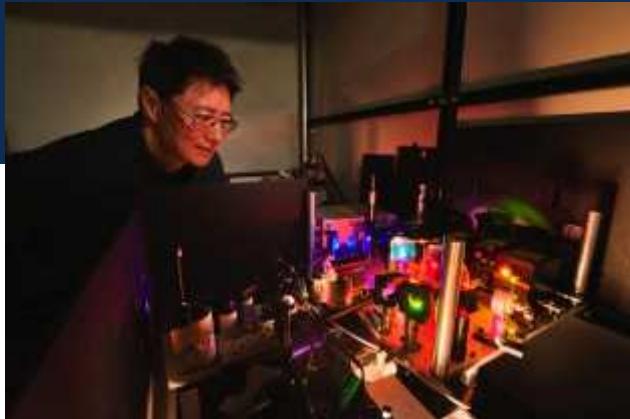


Exceptional service in the national interest



Securing Trusted Rad-Hard Electronics for the Future

Rich Dondero

Microsystems Assessments I

rdonder@sandia.gov

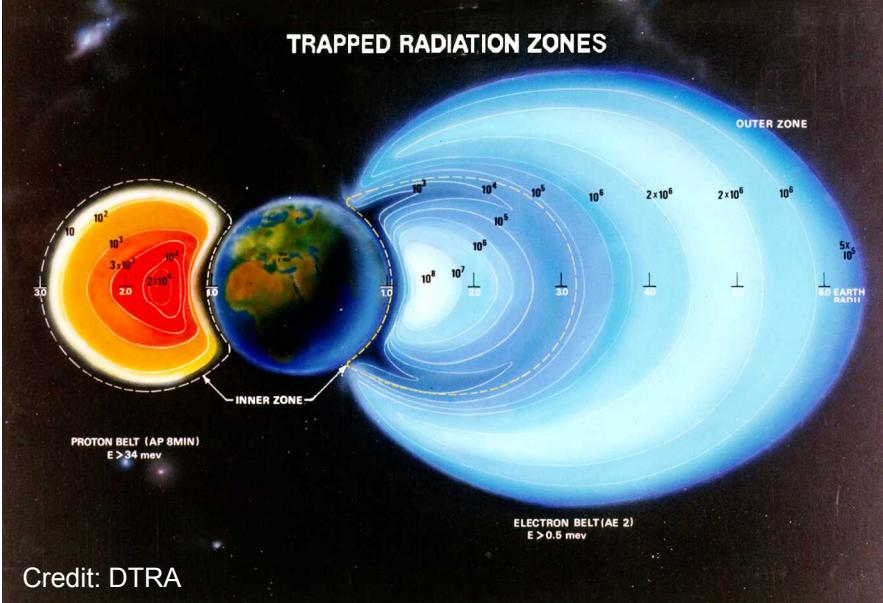
Sandia National Laboratories

DMSMS 2015

December 3, 2015



Sandia National Laboratories is a multi-program laboratory managed and operated by Sandia Corporation, a wholly owned subsidiary of Lockheed Martin Corporation, for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000. SAND2015-XXXX



Credit: DTRA

Microelectronics



Safe
Secure
Effective

Trust versus Trustworthiness

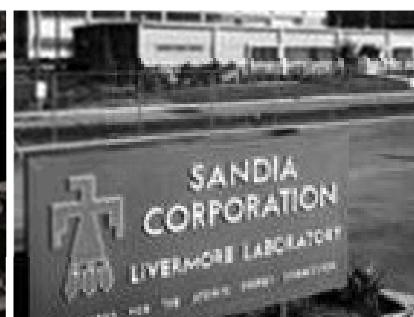
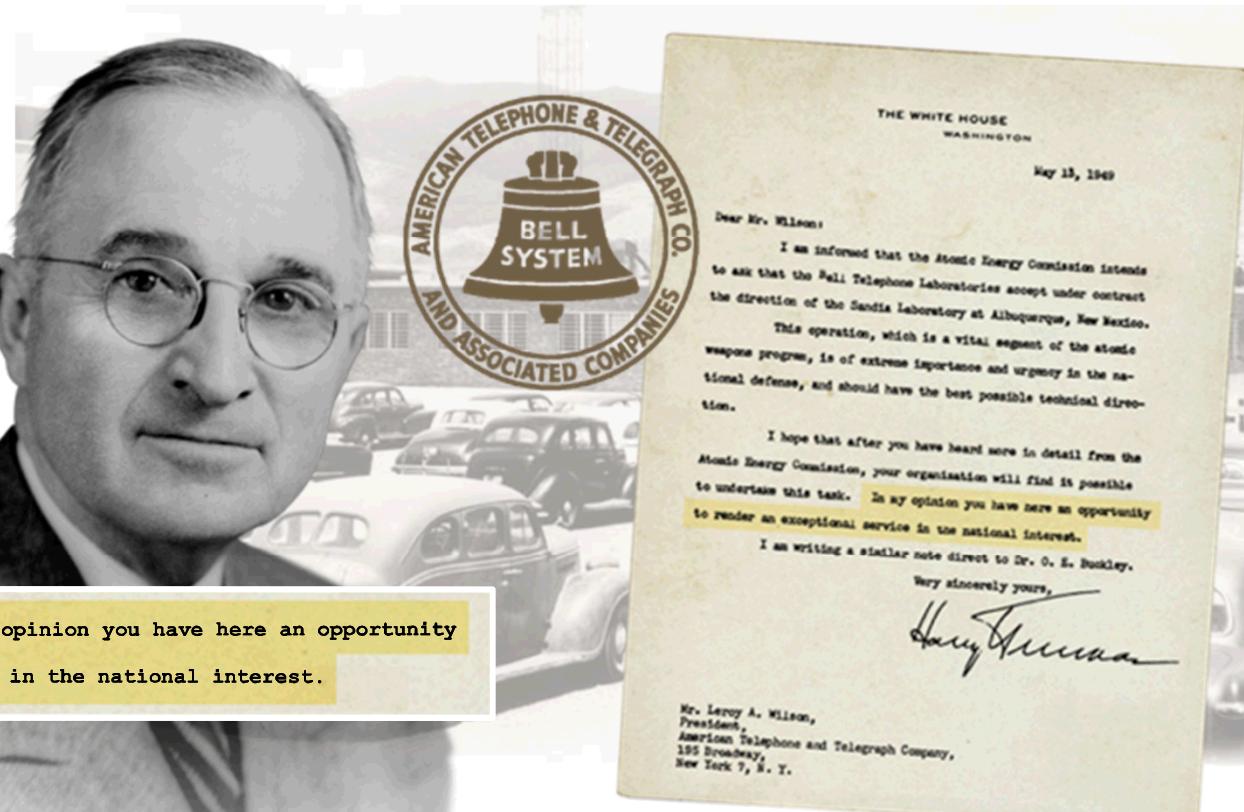


<http://www.superstock.com/stock-photography/Atomic+blast+military>

Sandia's History

Exceptional service in the national interest

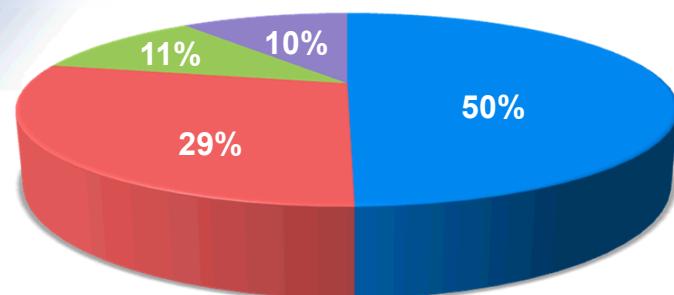
- July 1945: Los Alamos creates Z Division
- Nonnuclear component engineering
- November 1, 1949: Sandia Laboratory established



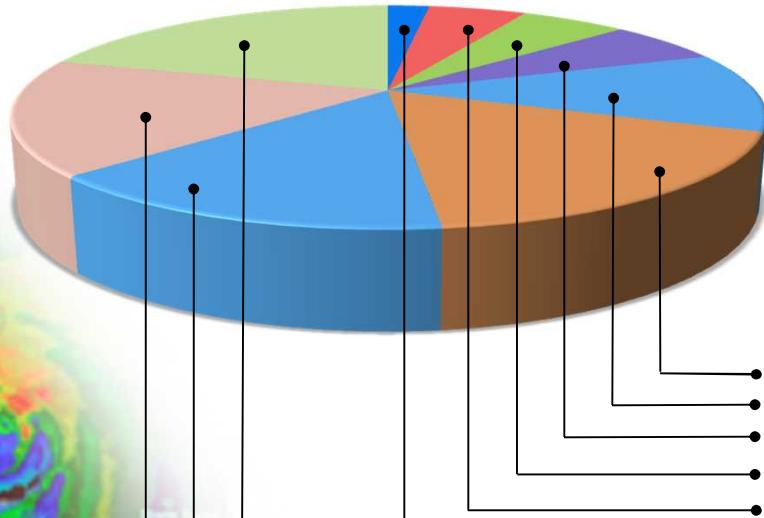
Sandia National Laboratories

- Total Sandia Workforce: 12,609
- Regular Employees: 10,330
- Advanced Degrees: 5,790 (56%)

**FY14 Operating Revenue
\$2.7 billion**



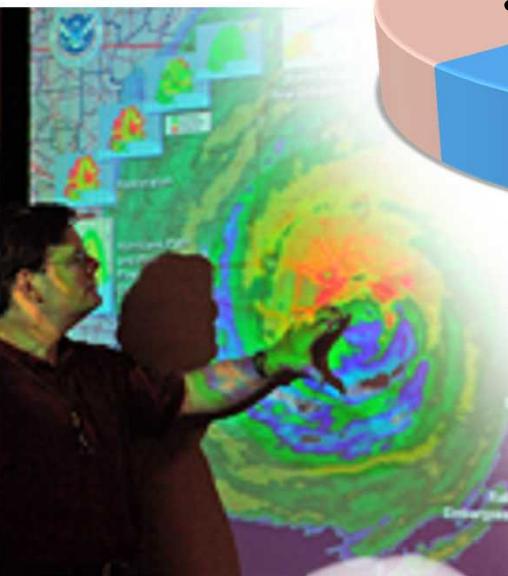
Technical staff (5,046) by discipline



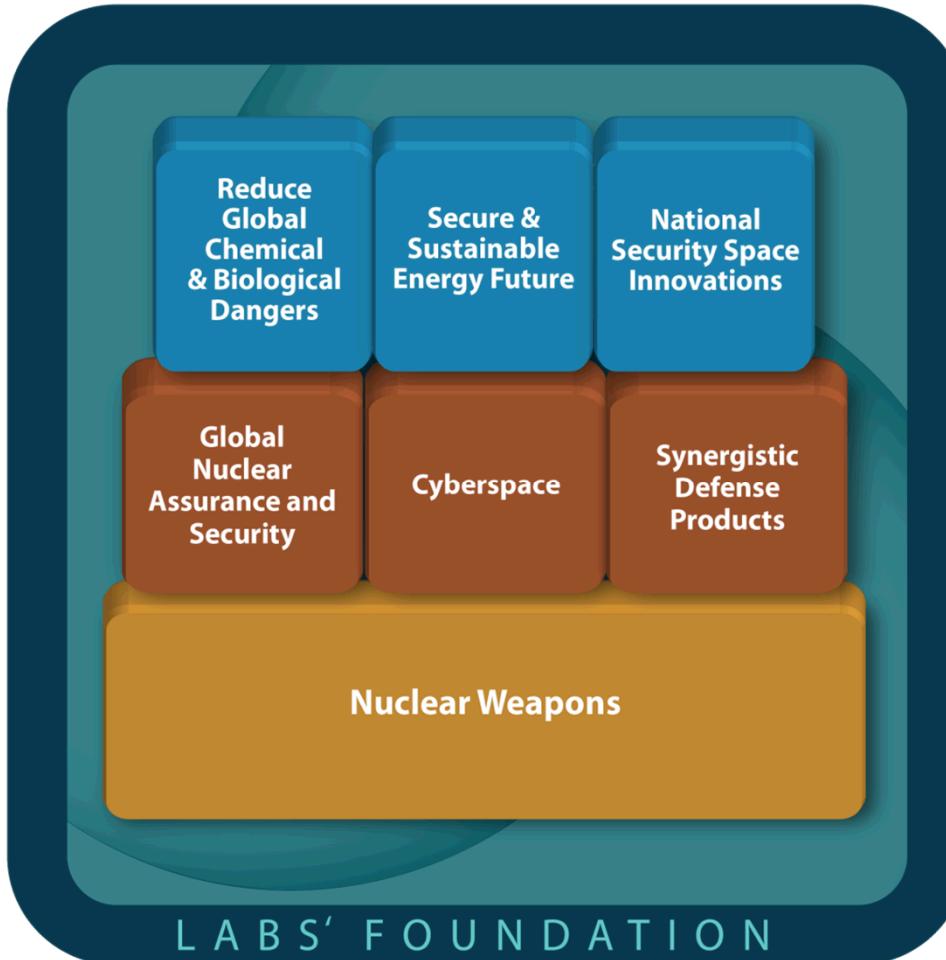
- Electrical Engineering 20%
- Mechanical Engineering 17%
- Other Engineering 15%

(Operating Budget)

- Nuclear Weapons
- Defense Systems & Assessments
- Energy, Climate & Infrastructure Security
- International, Homeland, and Nuclear Security



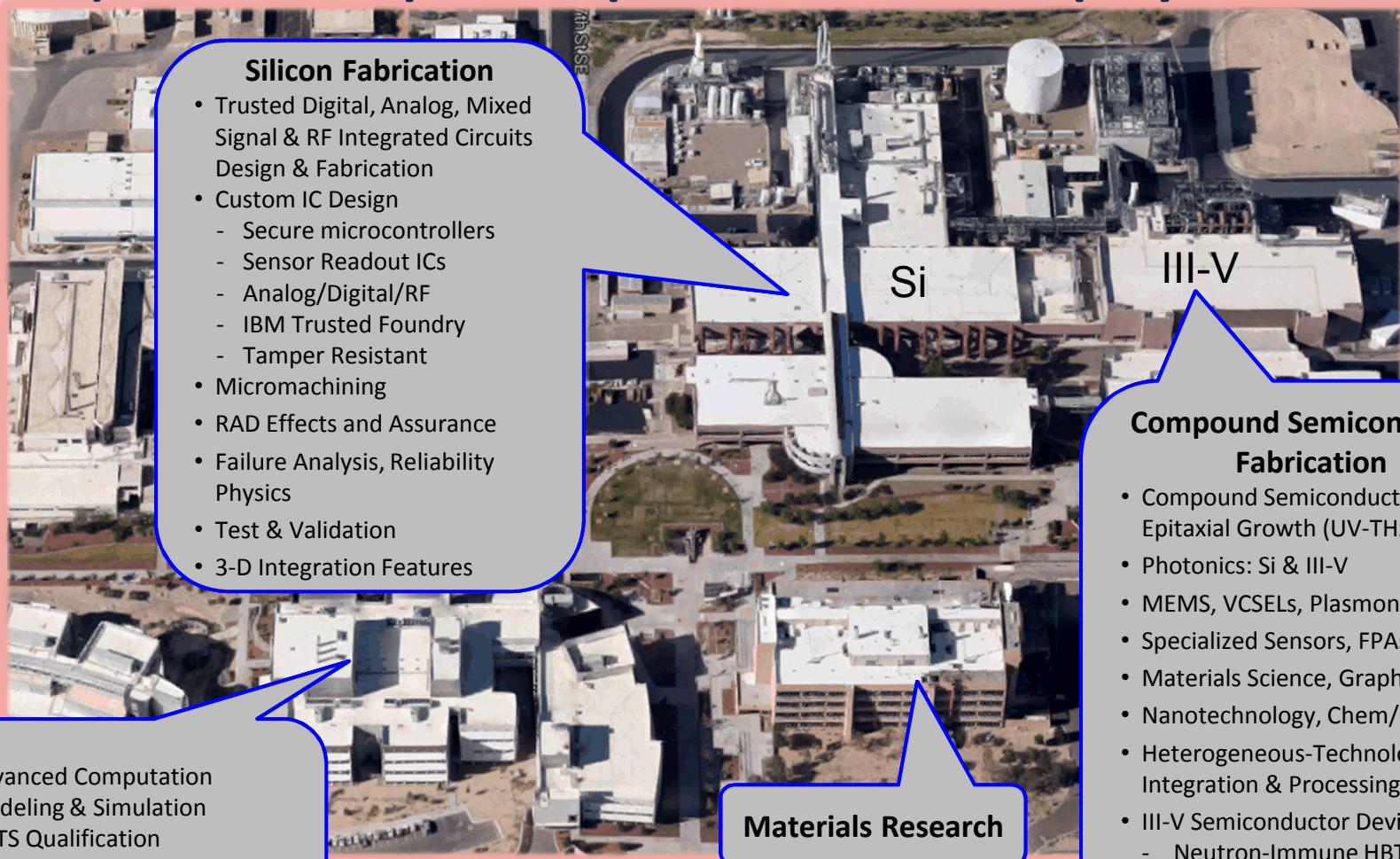
Seven National Security Mission Areas



Sandia accomplishes tasks that are integral to the mission and operation of our sponsoring agencies by:

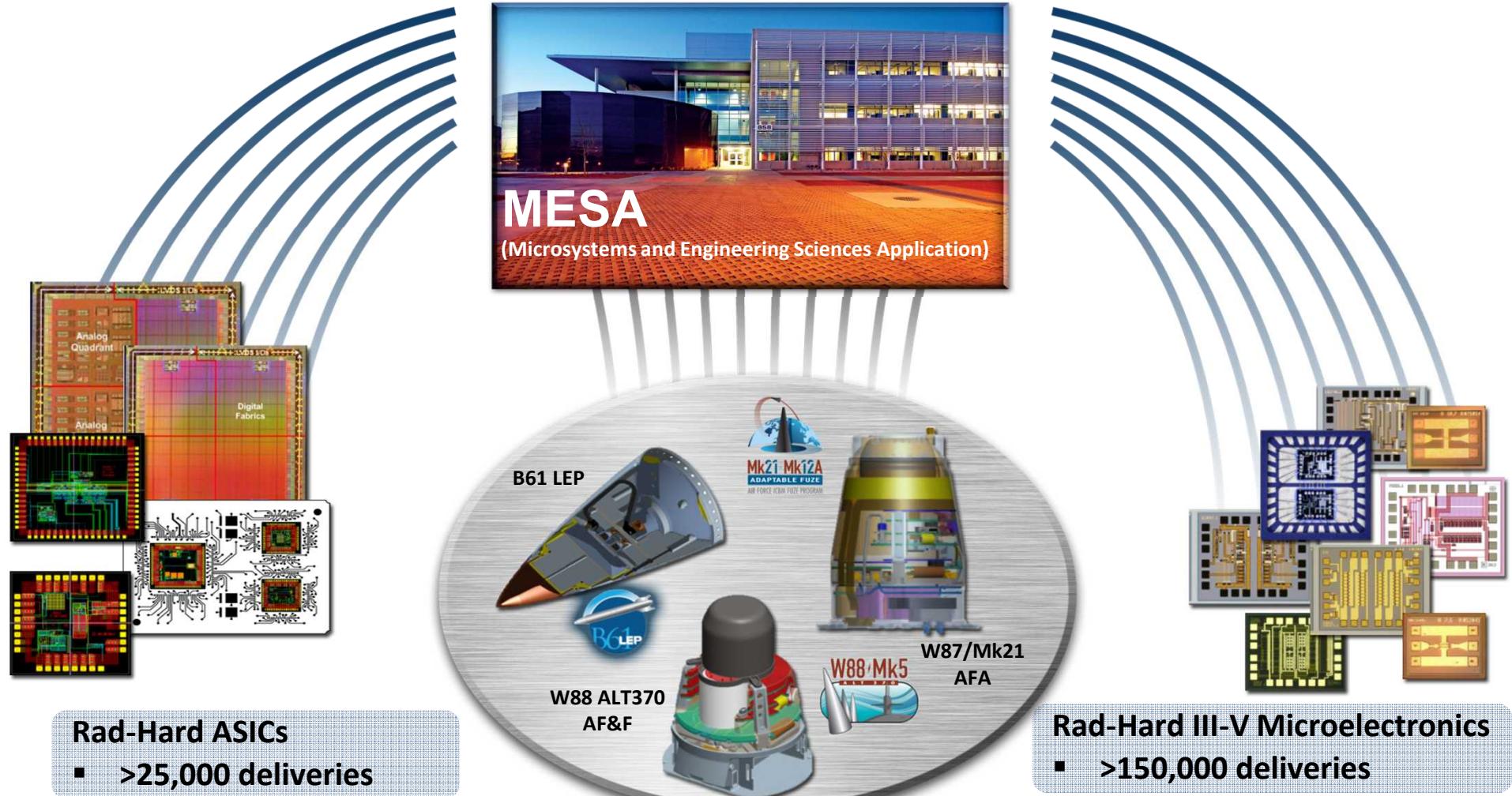
- Anticipating and resolving emerging national security challenges
- Innovating and discovering new technologies to strengthen the nation's technological superiority
- Creating value through products and services that solve important national security challenges
- Informing the national debate where technology policy is critical to preserving security and freedom throughout our world

Microsystems and Engineering Sciences Applications (MESA): 400,000 Sq-ft Complex with >650 Employees



MESA is an FFRDC-based development and production facility for any microsystem component or technology that cannot or should not be obtained commercially.

MESA Manufactures Strategic Rad-Hard Trusted Components for Nuclear Weapons



Trust Environment (NW, DMEA)

Strong Failure Analysis, Reliability

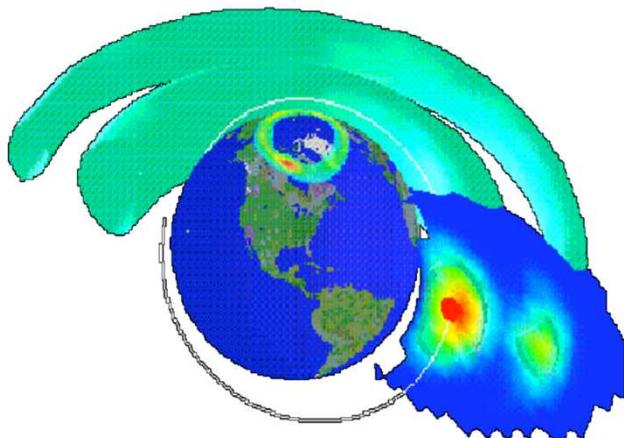
Table of Contents

- Radiation Environments
- Rad-Hard Solutions for Space
- Nuclear Weapon Radiation Environments
- Strategic Rad-Hard Solutions
- Trust
- Trust Solutions Today
- Trust Solutions Tomorrow
- Trust & Strategic Rad-Hard Futures
- Heterogeneous Solutions
- Supporting Framework

Space Radiation Environments

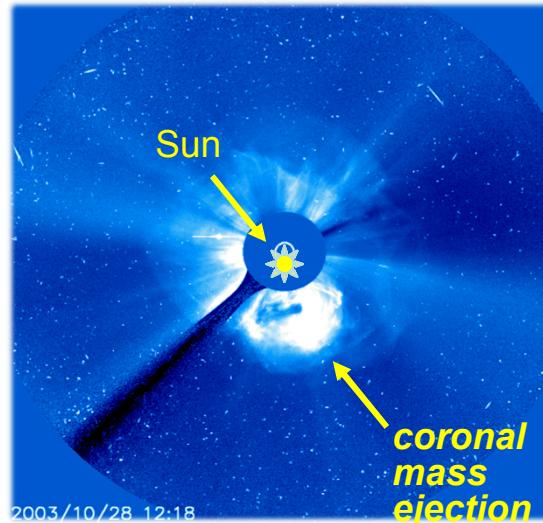
- The natural space radiation environment consists of trapped particle belts, solar events (flares and coronal mass ejections), and galactic cosmic rays
- Radiation can produce temporary malfunctions in electronics (e.g., single-event upset, single-event functional interrupts) or permanent degradation/failure (e.g., total ionizing dose, displacement damage, latchup/burnout)
- The impact of these effects can range from data corruption to instrument malfunction to mission failure

Trapped Particle Belts



J. Barth, 1997 NSREC

Solar Particle Events



SOHO (ESA & NASA)

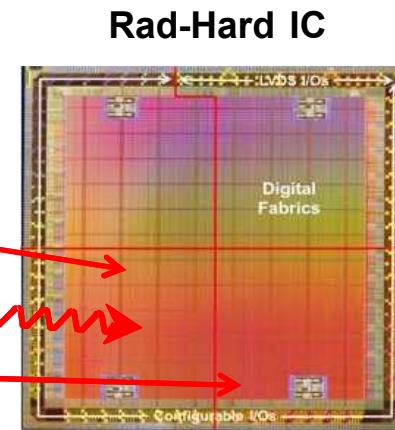
Galactic Cosmic Rays



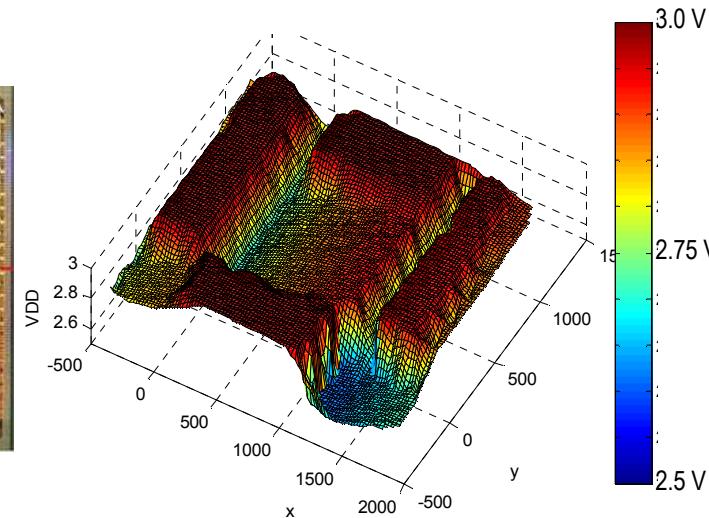
Pierre Auger Observatory

Nuclear Weapon Radiation Environments

- The radiation environment near a detonated nuclear weapon contains large numbers of x-rays, gammas, and neutrons
- Some effects of this environment are similar to those of the natural space environment but different in scale (e.g., displacement damage effects in bipolar transistors), while others are unique to this extreme environment (e.g., dose-rate upset in integrated circuits)
- Detonation of nuclear weapons in space can also affect operation and longevity of critical space assets (commercial and military)

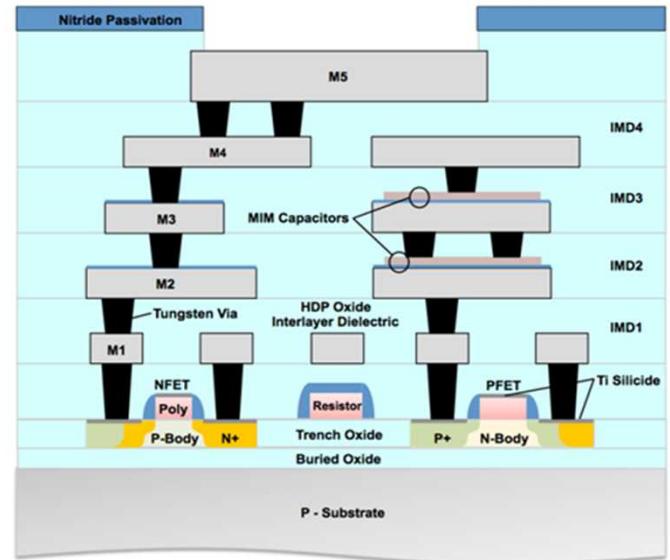


Simulated Rail Droop at High Dose Rate



Rad-Hard Solutions

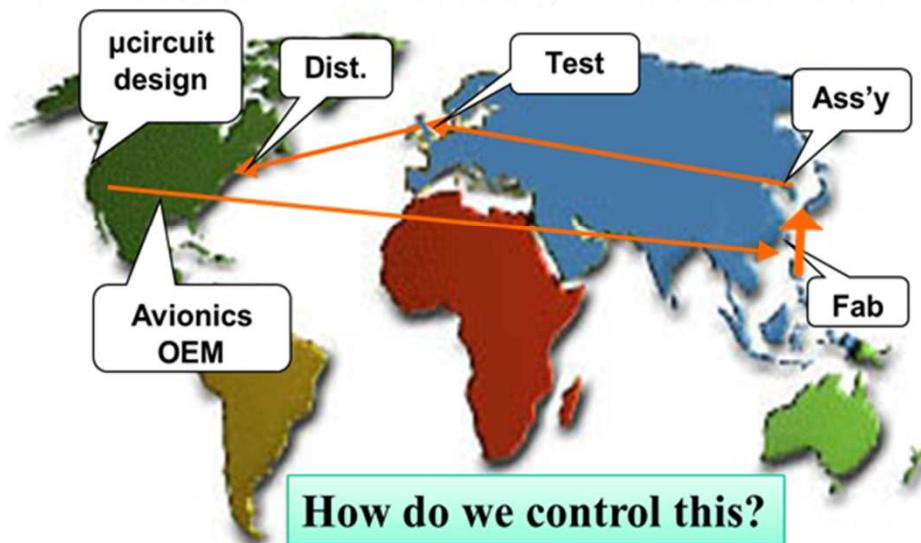
- Rad-Hard by Process (RHBP)
 - Honeywell: SOI CMOS at the 150-nm node, Rad-Hard products for satellite programs
 - ST Micro: Large portfolio of rad-tolerant products
- Rad-Hard by Design (RHBD)
 - Championed by Boeing, USAF, DTRA, and others
 - Provides radiation tolerance at the expense of density
 - Most RHBP technologies use some RHBD techniques
- Upscreening of COTS
 - Aeroflex/Cobham
- The solutions depend on the requirements
 - “Strategic” means different things to various customers
 - Strategic space vs. strategic nuclear weapons
 - Some hardness can be leveraged from space solutions, but additional techniques are required for some applications
- RHBP + RHBD
 - The total solution is usually a combination of both techniques
- Generally the solution space is small
 - Honeywell, BAE Systems, Boeing Design Kit, Sandia National Laboratories, Northrop Grumman



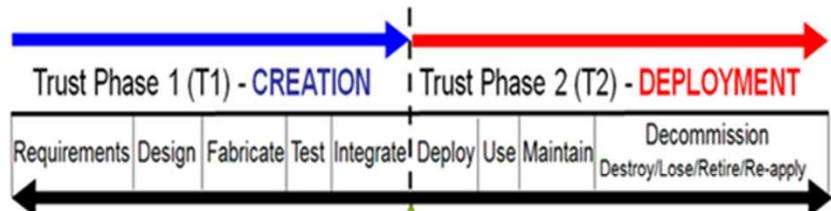
Sandia's SOI CMOS7 Rad-Hard Technology

Trust: The Issues

- Counterfeit parts are big business - Legacy parts
- Cloning is becoming a serious threat – not easy to detect
- The rise of malicious intent: denial of service, kill switches, and inclusion of hidden communications ports
- Circuitous supply chain – where is the chain of custody



Syd Pope (ODUSD/IP), GOMAC 2009



Trust Solutions Today

- DMEA Accredited Trusted Foundry
 - Global Foundries US 2
 - Formerly IBM TF: 52 Designs
 - Trusted Access Program Office (TAPO)
- DMEA Accredited Trusted Suppliers
 - Design through package parts
 - Roughly 63 accredited suppliers
- Legacy Parts – know your supply chain
 - SRI, Lansdale Semiconductor
- Counterfeit Detection – Verification/Validation
 - Several government and commercial services
 - Fairly straightforward methods
 - Counterfeitors adapt to detection techniques
 - Cloning detection – challenging

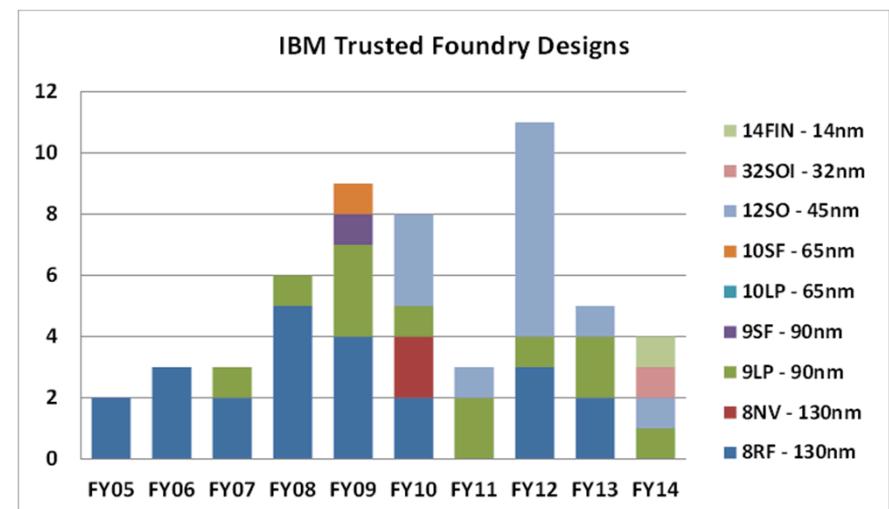


NORTHROP GRUMMAN

LANSDALE
Semiconductor Inc.

TOWERJAZZ
The Global Specialty Foundry Leader

Honeywell | Aerospace



Trust Solutions Tomorrow

- DMEA accredited, Trusted Microsystems suppliers will continue
 - In a challenging environment manufacturers continue to move off-shore or shut down
 - Manufacturer consolidation increases foreign ownership
 - Access to trusted state-of-the-art microelectronics is in jeopardy
- State-of-the-art moves off-shore or is foreign owned – How to mitigate?
 - IARPA – TIC: Split BEOL/FEOL manufacturing flow
 - SHIELD: Provide a secure hardware root-of-trust which co-packaged with an electronic component
 - CRAFT: Significantly increase reuse of integrated circuit elements (IP)
 - Diverse and Accessible Heterogeneous Integration: Manufacturing a device across multiple commercial locations while concealing its functionality
- Areas of Opportunity
 - Trust Metrics – when to use what
 - Trust Resiliency
 - Obfuscation Techniques
 - Fast Assurance Techniques

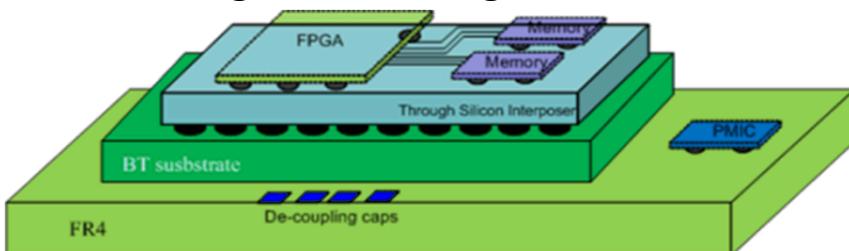


I A R P A

Sandia's Trust & Strategic Rad-Hard Futures



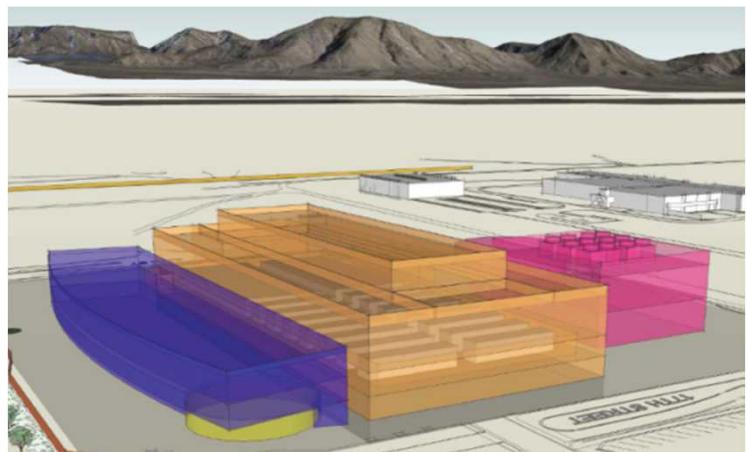
- Developing 180/150nm Technology
 - Based on BAE's technologies, but on SOI
 - Upgrading our silicon fab to process 200mm wafers
 - Strategic hardness with improved speed and density
- Planning a Future Capability
 - Can CMOS be strategic rad-hard at 90nm?
 - Sweet spot identified by customers for both analog and digital applications
 - Tradeoffs in cost, yield, and performance need to be addressed
 - Includes CMOS fab, advanced packaging, design, and test
 - Should it be scalable to 300mm?
 - Possibly for split-fab back-end-of-line
 - Expanded R&D capabilities
 - Heterogeneous Integration



Stacking & Heterogeneous Integration



MESA Complex



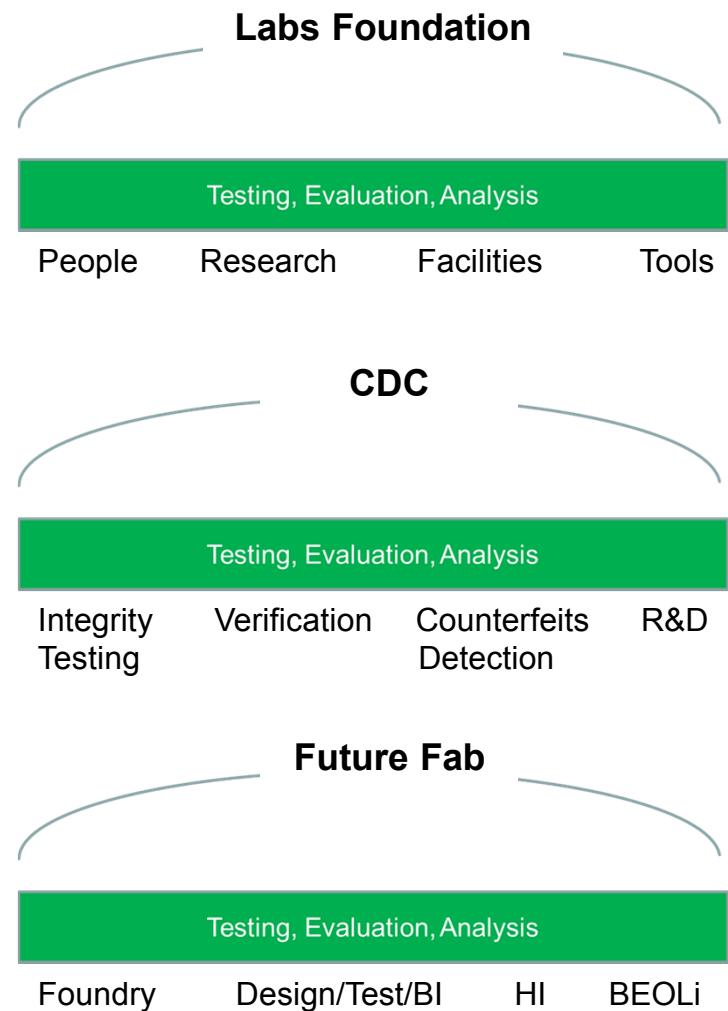
Next Generation Facility

For NW, Trusted Services Alone is Not the Answer

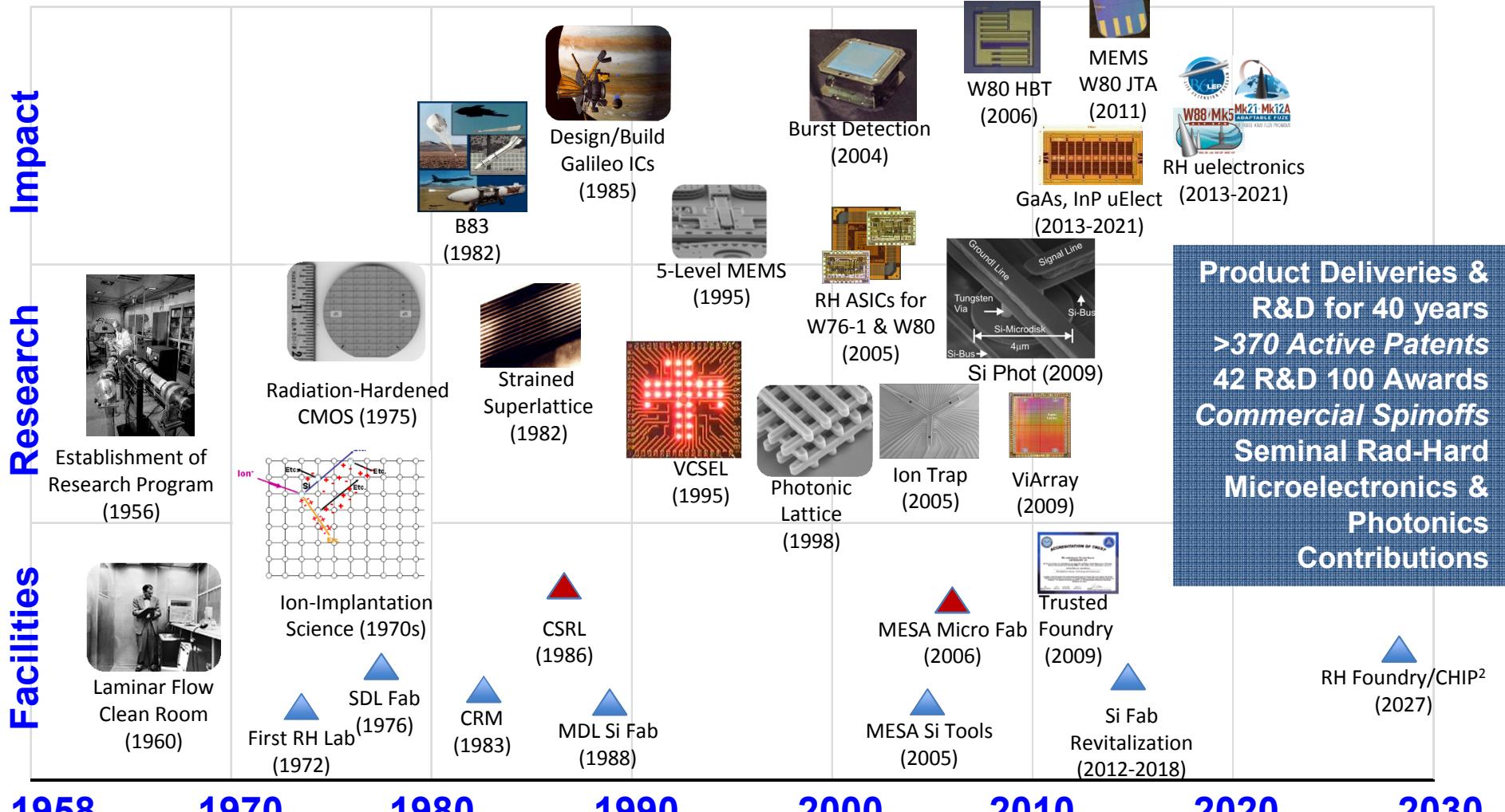
- A holistic approach is required for microelectronics
 - Fortification of the Supply Chain - Pedigree
 - Verification & Validation that the part does nothing more and nothing less than intended reliably
 - Assurance that what you designed is what you get - ASIC
 - Deterrence of Malicious intent – through attribution, policy
 - Cradle to Grave verification
- Research & Development, Advanced Capabilities & Talent are necessary
 - RHBD techniques
 - New RHBP methods
 - Materials
 - Imaging Techniques
 - Data Processing
 - Packaging
 - Assessments
 - Software Engineering
 - Red Teaming

Counterfeit Detection Center (CDC)

- An R&D facility that deals with counterfeit detection supporting SNL mission areas



R&D Enables and Sustains Sandia's Rad-Hard Microelectronics/Microsystems Capability



MISSION: Invent and mature integrated circuit and microsystems technologies that provide differentiation and impact for NW and other national security missions

Summary

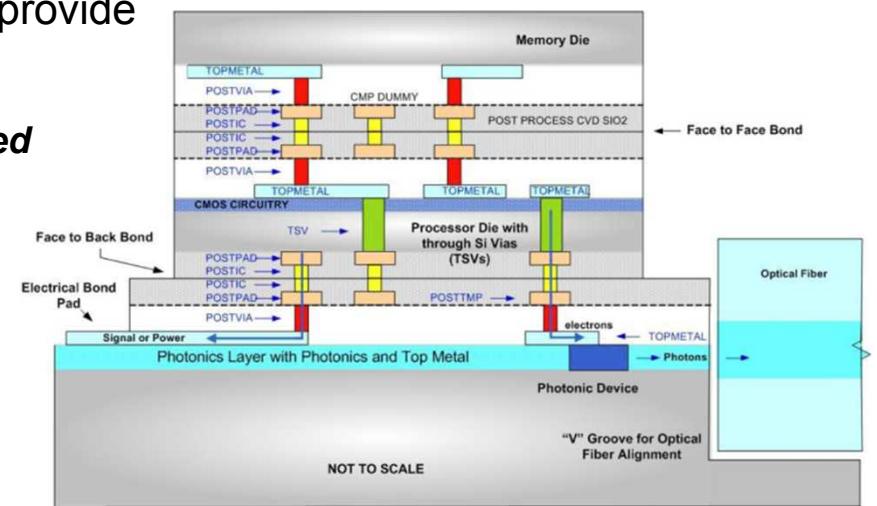
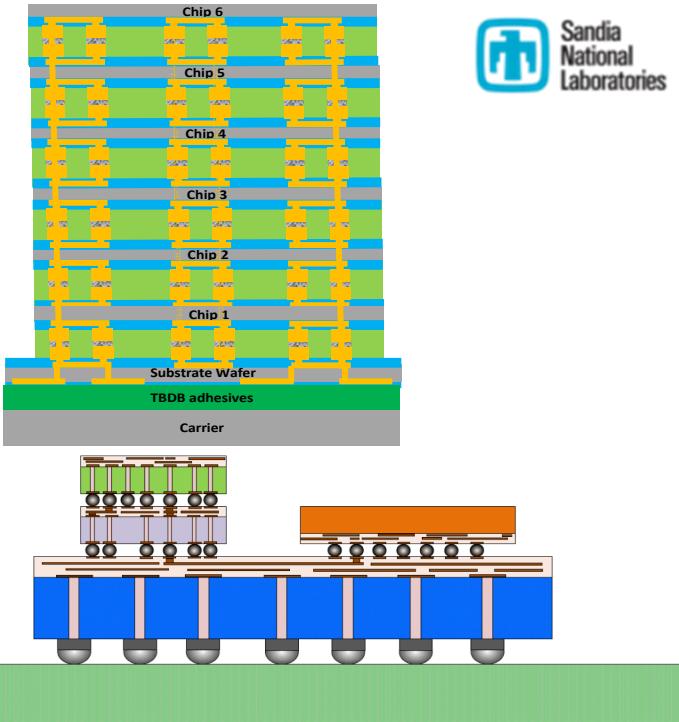
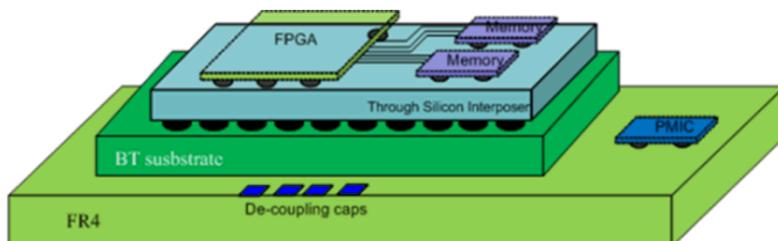
- Electronics must withstand radiation to minimize the possibility of malfunction in both space and nuclear weapon environments
- Solutions include Radiation-Hardened By Process and Radiation-Hardened By Design, sometimes both
- Solution space is small
- The supply chain is circuitous, therefore raising concerns about the integrity of parts
- There are many rad-hard trusted foundries, although the solution also includes design, supply chain and manufacturing
- There is ongoing R&D to ensure the creation of trusted circuits and a secure supply chain
- We propose to define foundational techniques for supporting analysis of trustworthiness, and for improving trust through diversification.
- The future of trusted rad-hard technologies is uncertain, however, Sandia is engaged in creating solutions
- Measuring and engineering trust presents difficult research problems with national-scale impact. Sandia is ideally suited to address these complexities due to its long history of developing highly reliable systems and understanding nation-state threats

Extra Slides

2.5-D and 3-D Solutions

- Chip stacking can be used to increase the effective areal density. For example, stacking multiple rad-hard CMOS chips manufactured at the 180-nm node could provide the same or better functionality and footprint compared to a single chip manufactured at the 32-nm node, but at reduced production cost.
- 2.5-D integration combine disparate technologies on a single substrate.
- 3-D heterogeneous integration can be used to combine traditional rad-hard ICs with photonics, compound semiconductors, and MEMS components to provide new functionality.

All of these techniques can be used to create trusted systems out of untrusted components.



Schematic of a potential 3D stacked photonics, processor, and memory structure

Sandia Addresses National Security Challenges

Sandia's Mission: Our unique mission responsibilities in the nuclear weapons (NW) program create a foundation from which we leverage capabilities, enabling us to solve complex national security problems.

1950s

Nuclear weapons

Production and manufacturing engineering

1960s

Development engineering

Vietnam conflict

1970s

Multiprogram laboratory

Energy crisis

1980s

Missile defense work

Cold War

1990s

Post-Cold War transition

Stockpile stewardship

2000s

START Post 9/11

National security

2010s

LEPs
Cyber, biosecurity proliferation

Evolving national security challenges



Defense Systems & Assessments Programs

Information Operations



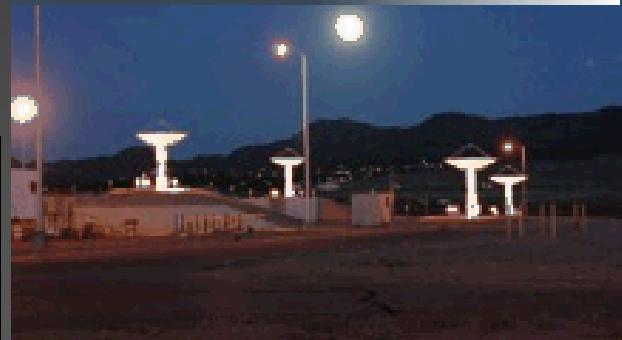
Surveillance & Reconnaissance



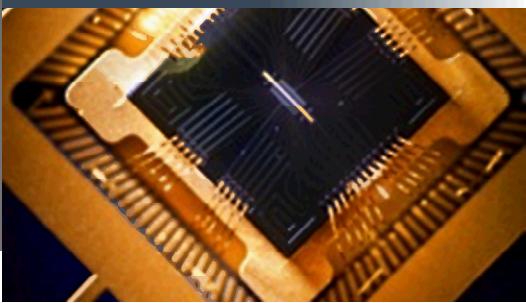
Remote Sensing and Verification



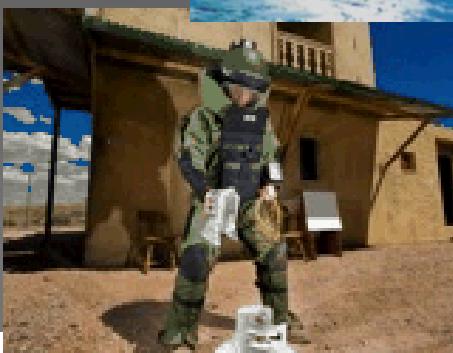
Space Mission



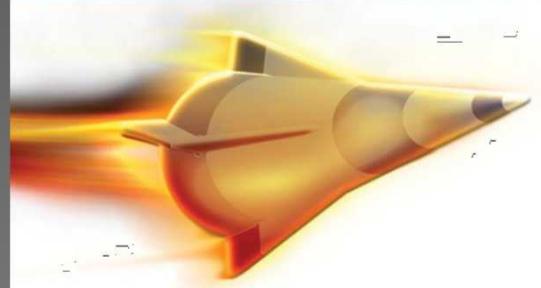
Science & Technology Products



Proliferation Assessment



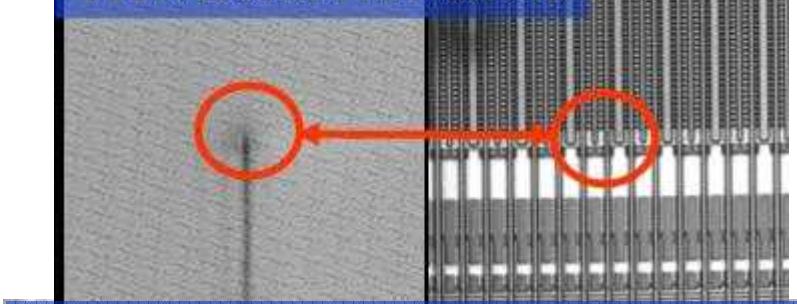
Integrated Military Systems



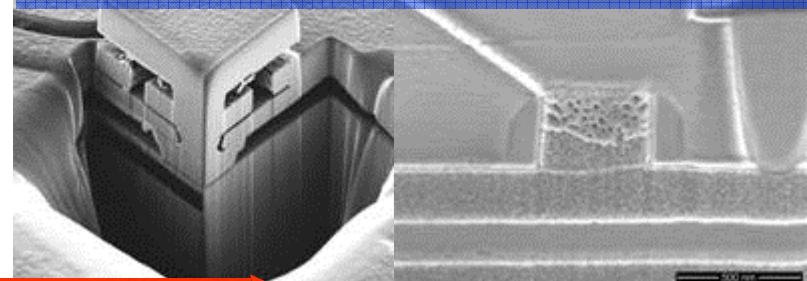
Counterfeit Detection Center

- Expertise in Si CMOS, III-V, MEMS, and Optoelectronics
 - Component and now board-level
- Sandia developed techniques now industry standards (LIVA, TIVA, SDL, etc.)
- Deprocessing, and build analysis capabilities
- Support through entire product life cycle
- Extensive reliability & FA capabilities, equipment, tools, & techniques

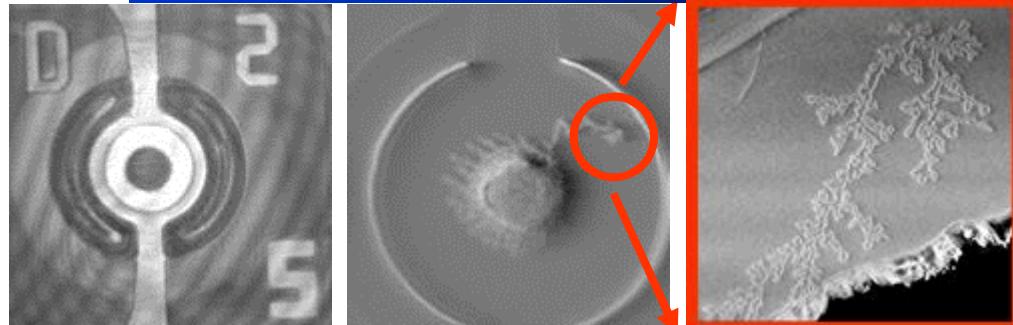
TIVA Defect Isolation



FIB for Imaging & Circuit Editing



TIVA and STEM for Optoelectronic Failure Analysis



Soft Defect Localization (SDL)

